YENYO

S1AF THRU S1MF
1.0A General Purpose Rectifier

1. 封裝 Package

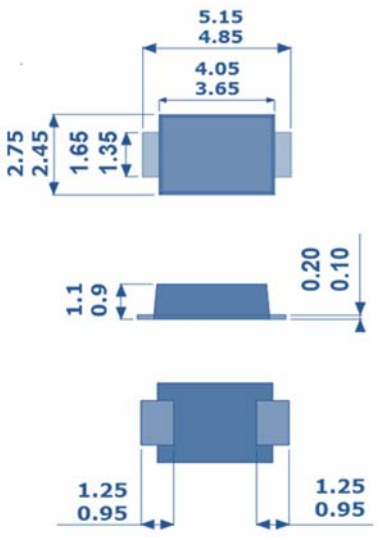
- 封裝方式 Method: SMAF
- 封裝尺寸 Dimension: 如圖示

2. 產品特色 Features

- Low Forward voltage drop
- Easy pick and place
- High temperature soldering: 260℃/10 seconds at terminals
- Ultra thin profile package for space constrained utilization
- Package suitable for automated handling
- Glass passivated chip junction
- For surface mounted applications in order to optimize board space
- Lead-free & halogen-free parts, RoHS compliant

3. 機械數據 Mechanical Data

- Epoxy: UL94V-0 rated flame retardant
- Case: Molded Plastic
- Terminals: Solder plated solderable per MIL-STD-750 Method 2026
- Mounting position: Any
- Polarity: Color band denotes cathode end



單位 Unit: millimeters

4. 極限值與電參數 Maximum Ratings & Electrical Characteristic

Rating at 25^{O}C ambient temperature unless otherwise specified. Single phase, half wave, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%.

PARAMETER	Symbol	S1AF	S1BF	S1DF	S1GF	S1JF	S1KF	S1MF	UNITS
Repetitive Peak Reverse Voltage	V_{RRM}	50	100	200	400	600	800	1000	Volts
RMS Voltage	V_{RMS}	35	70	140	280	420	560	700	Volts
DC Blocking Voltage	V_R	50	100	200	400	600	800	1000	Volts
Average Forward Current	$I_{F(AV)}$	1.0							Amps
Peak Forward Surge Current :8.3ms single half sine-wave superimposed on rated load	I_{FSM}	30.0							Amps
Forward voltage at 1.0A	V_F	1.1							Volts
DC Reverse Current T_J=25^{O}C DC blocking voltage	I_R	3							uA
Typical thermal resistance, Junction to lead(Note 1)	$R_{\theta JL}$	20							^{O}C/W
Junction to ambient (Note 1)	$R_{\theta JA}$	83							
Operating junction temperature and storage temperature range	T_J, T_{STG}	-55 to +150							^{O}C

Notes:

(1) Mounted on 48 cm^2 FR-4 PCB.

5. 特性曲線 Rating & Characteristic Curves

Fig. 1 Forward Current Derating Curve

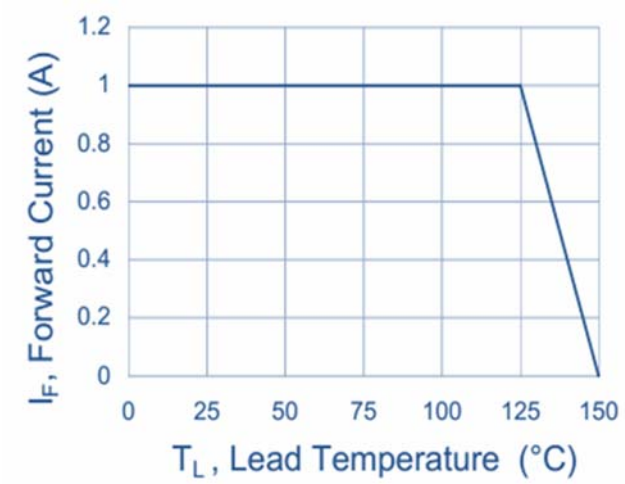


Fig. 2 Typical Reverse Characteristics

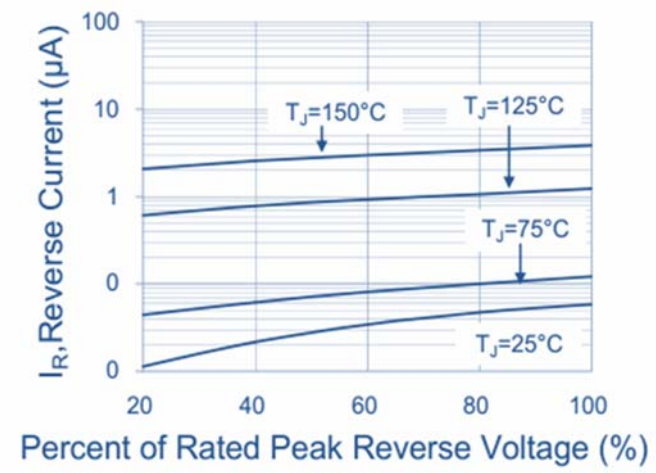


Fig. 3 Typical Forward Characteristics